

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S47	292	(chip or die) adj capacitor same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:59
S14	268	(chip or die) adj capacitor same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:59
S46	116	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:48
S13	108	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:48
S45	369	surface near mount near capacitor	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:14
S6	343	surface near mount near capacitor	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/07 15:11
S44	195	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:52
S4	188	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:52
S43	19	257/795.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:47
S42	32	257/793.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:47
S41	29	257/789.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:44
S40	192	257/783.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:40
S39	228	257/778.cor. and (underfill or underfilling)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:29

S38	732	257/778.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:02
S37	47	257/747.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:01
S36	393	257/738.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 14:00
S35	525	257/737.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 13:38
S1	17	(passive near3 device or smd or resistor or capacitor or diode) near6 (bonded or flip adj chip or mounted or mount) near10 (noflow or no-flow or reflow or preform or preformed) near6 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 13:03